

A Wafer Bonded Virtual Substrate and Method for Forming the Same

Harry A. Atwater, Jr. et al. Appl. No.: 10/761,918 Atty. Dkt. CIT.PAU.05A

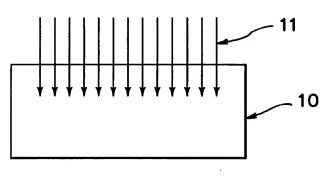
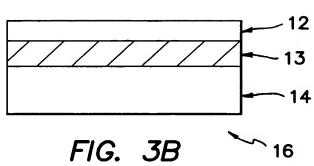


FIG. 3A



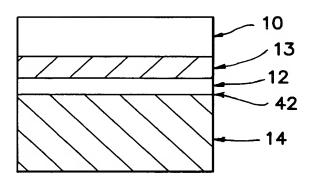


FIG. 4A

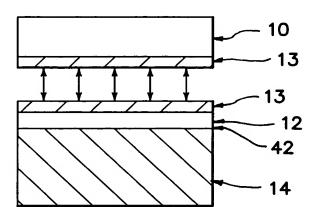
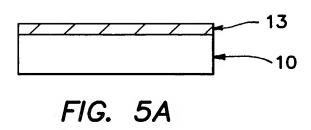
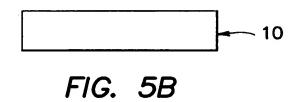
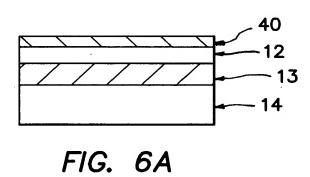
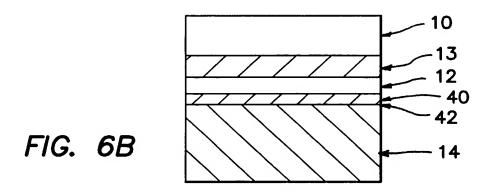


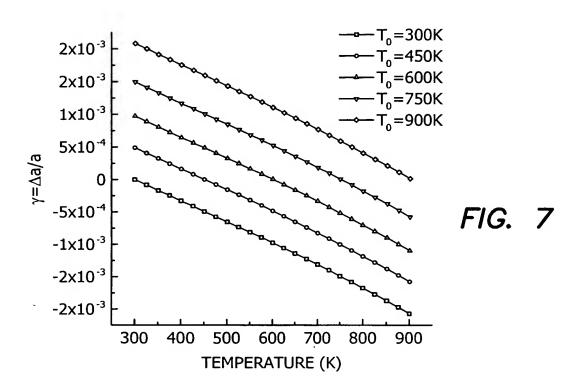
FIG. 4B

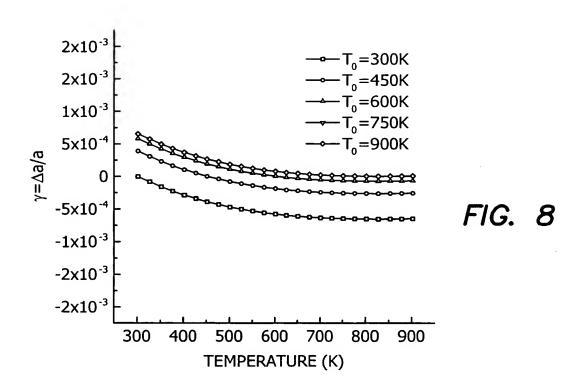


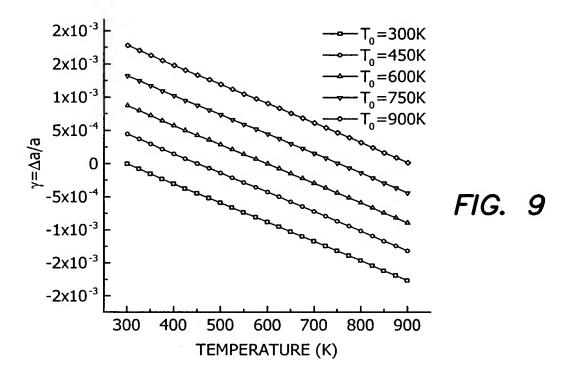


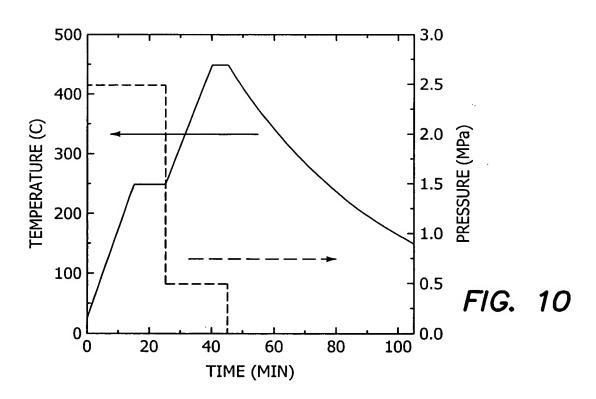




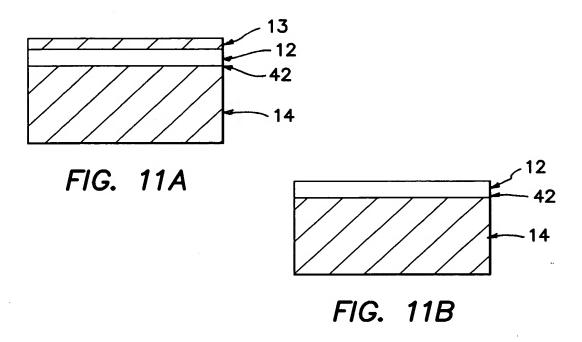








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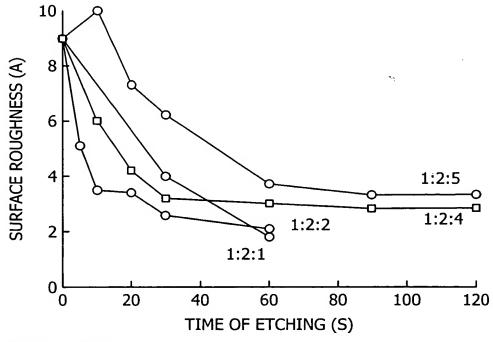
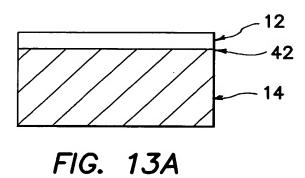
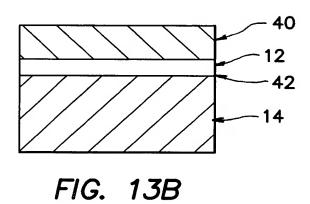


FIG. 12

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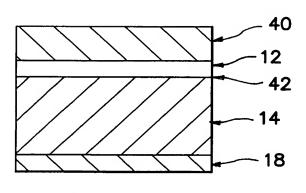


FIG. 14